

# WIDE BAND LOW NOISE AMPLIFIER GAAS MMIC

### **■** GENERAL DESCRIPTION

The NJG1142KA1 is a wide band low noise amplifier GaAs MMIC designed for mobile TV application. And this amplifier can be tuned to wide frequency (170MHz~900MHz).

The NJG1142KA1 has a LNA pass-through function to select high gain mode or low gain mode by low control voltage operation. The NJG1142KA1 features low current consumption, high linearity.

An ultra-small and ultra-thin package of FLP6-A1 is adopted.

# ■ PACKAGE OUTLINE



NJG1142KA1

### **■ APPLICATIONS**

Wide band applications from 170MHz to 900MHz Mobile TV and Digital TV applications Mobile phone and tablet PC applications

#### **■ FEATURES**

Wide operating frequency range
 Low voltage operation
 170MHz~900MHz
 +2.8V/+1.8V typ.

[High gain mode]

• Low current consumption	6mA typ.	@Vdd=2.8V
● High gain	+14.0dB typ.	@Vdd=2.8V
<ul><li>Low noise figure</li></ul>	1.5dB typ.	@Vdd=2.8V
● High P <sub>-0.1dB</sub> Compression	0dBm typ.	@Vdd=2.8V
<ul><li>High input IP3</li></ul>	+2.0dBm typ.	@Vdd=2.8V

[Low gain mode]

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<ul><li>Low current consumption</li></ul>	11μA typ.	@Vdd=2.8V
■ Gain (Low loss)	-1.0dB typ.	@Vdd=2.8V
● High P <sub>-0.1dB</sub> Compression	+17dBm typ.	@Vdd=2.8V
High input IP3	+22.0dBm typ.	@Vdd=2.8V

External components count

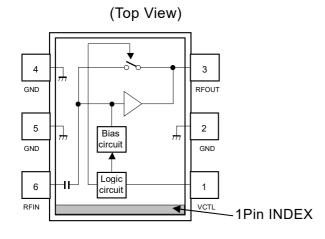
3 pcs. (capacitor: 2pcs, inductor: 1pc)

Small package size

FLP6-A1 (package size: 1.6mm x 1.6mm x 0.55mm typ.)

RoHS compliant and Halogen Free

### **■ PIN CONFIGURATION**



### **■ PIN CONNECTION**

- 1. VCTL
- 2. GND
- 3. RFOUT
- 4. GND
- 5. GND
- 6. RFIN

#### **■ TRUTH TABLE**

"H" =  $V_{CTL(H)}$  "L" =  $V_{CTL(L)}$ 

V <sub>CTL</sub>	LNA Mode
Н	High Gain Mode
L	Low Gain Mode

NOTE: The information on this datasheet is subject to change without notice

# **NJG1142KA1**

## ■ ABSOLUTE MAXIMUM RATINGS

 $T_a=+25$ °C,  $Z_s=Z_l=50$  ohm

PARAMETER	SYMBOL	CONDITIONS	RATINGS	UNITS
Supply voltage	$V_{DD}$		5.0	V
Control voltage	$V_{CTL}$		5.0	V
Input power	P <sub>IN</sub>	V <sub>DD</sub> =2.8V	+15	dBm
Power dissipation	P <sub>D</sub>	4-layer FR4 PCB with through-hole (74.2mmx74.2mm), T <sub>j</sub> =150°C	580	mW
Operating temperature	$T_{opr}$		-40~+85	°C
Storage temperature	$T_{stg}$		-55~+150	°C

# ■ ELECTRICAL CHARACTERISTICS 1 DC CHARACTERISTICS

General conditions:  $V_{DD}=2.8V$ ,  $T_a=+25$ °C,  $Z_s=Z_l=50$  ohm, with application circuit

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PARAMETERS	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Operating voltage	$V_{DD}$		2.3	2.8	3.6	V
Control voltage (High)	V <sub>CTL(H)</sub>		1.3	1.8	3.6	V
Control voltage (Low)	$V_{\text{CTL}(L)}$		0.0	0.0	0.5	V
Operating current1	I <sub>DD1</sub>	RF OFF, V <sub>CTL</sub> =1.8V	-	6.0	9.5	mA
Operating current2	I <sub>DD2</sub>	RF OFF, V <sub>CTL</sub> =0V	-	11.0	25.0	μΑ
Control current	I <sub>CTL</sub>	RF OFF, V <sub>CTL</sub> =1.8V	-	6.0	10.0	μА

# ■ ELECTRICAL CHARACTERISTICS 1 RF CHARACTERISTICS1 (High Gain Mode)

Conditions:  $V_{DD}$ =2.8V,  $V_{CTL}$ =1.8V,  $f_{RF}$ =170~900MHz,  $T_a$ =+25°C,  $Z_s$ = $Z_l$ =500hm, with application circuit

PARAMETERS	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Small signal gain1	Gain1	Exclude PCB, connector losses*1	11.0	14.0	18.0	dB
Noise figure1	NF1	Exclude PCB & connector losses*2	-	1.5	1.9	dB
Input power 1dB gain compression1	P <sub>-1dB(IN)</sub> 1		-5.0	0.0	1	dBm
Input 3rd order intercept point1	IIP3_1	$f1=f_{RF}$ , $f2=f_{RF}+100$ kHz, $P_{IN}=-26$ dBm	-3.0	+2.0	-	dBm
Isolation1	ISL1	Exclude PCB & connector losses*1	-	-19	-	dB
RF IN VSWR1	VSWRi1		-	1.5	2.3	-
RF OUT VSWR1	VSWRo1		-	1.5	2.2	-

<sup>\*1</sup> Input & output PCB and connector losses:

0.018dB(170MHz), 0.044dB(620MHz), 0.060dB(900MHz)

# ■ ELECTRICAL CHARACTERISTICS 1 RF CHARACTERISTICS2 (Low Gain Mode)

Conditions: V<sub>DD</sub>=2.8V, V<sub>CTL</sub>=0V, f<sub>RF</sub>=170~900MHz, T<sub>a</sub>=+25°C, Z<sub>s</sub>=Z<sub>I</sub>=50ohm, with application circuit

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PARAMETERS	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Small signal gain2	Gain2	Exclude PCB & connector losses*1	-2.5	-1.0	-	dB
Input power at 1dB gain compression2	P-1dB(IN)2		+14.0	+17.0	-	dBm
Input 3rd order intercept point2	IIP3_2	$f1=f_{RF}$ , $f2=f_{RF}+100$ kHz, $P_{IN}=-8$ dBm	+17.0	+22.0	-	dBm
RF IN VSWR2	VSWRi2		-	1.5	2.0	-
RF OUT VSWR2	VSWRo2		-	1.5	2.0	-

<sup>\*1</sup> Input & output PCB and connector losses:

0.035dB(at 170MHz), 0.088dB(620MHz), 0.120dB(at 900MHz)

<sup>0.035</sup>dB(at 170MHz), 0.088dB(620MHz), 0.120dB(at 900MHz)

<sup>\*2</sup> Input PCB and connector losses:

# **NJG1142KA1**

## ■ ELECTRICAL CHARACTERISTICS 2 DC CHARACTERISTICS

General conditions: $V_{DD}$ =1.8V, $T_a$ =+25°C, $Z_s$ = $Z_l$ =50 ohm, with application circuit						
PARAMETERS	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Operating voltage	$V_{DD}$		-	1.8	ı	V
Control voltage (High)	$V_{\text{CTL(H)}}$		-	1.8	1	V
Control voltage (Low)	$V_{\text{CTL}(L)}$		-	0.0	1	V
Operating current1	I <sub>DD1</sub>	RF OFF, V <sub>CTL</sub> =1.8V	-	4.2	1	mA
Operating current2	I <sub>DD2</sub>	RF OFF, V <sub>CTL</sub> =0V	-	6.4	1	μА
Control current	I <sub>CTL</sub>	RF OFF, V <sub>CTL</sub> =1.8V	-	5.6	-	μΑ

# ■ ELECTRICAL CHARACTERISTICS 2 RF CHARACTERISTICS1 (High Gain Mode)

Conditions:  $V_{DD}=1.8V$ ,  $V_{CTL}=1.8V$ ,  $f_{RF}=170\sim900$ MHz,  $T_a=+25$ °C,  $Z_s=Z_l=50$ ohm, with application circuit **PARAMETERS** SYMBOL **CONDITIONS** MIN TYP MAX **UNITS** Exclude PCB, connector Small signal gain1 12.1 Gain1 dB losses\*1 Exclude PCB & connector NF1 Noise figure1 1.75 dB losses\*2 Input power 1dB gain -1.6 dBm  $P_{-1dB(IN)}1$ compression1  $f1=f_{RF}$ ,  $f2=f_{RF}+100kHz$ , Input 3rd order IIP3 1 +2.0 dBm intercept point1  $P_{IN}$ =-26dBm Exclude PCB & connector Isolation1 ISL1 -18.4 dB losses\*1 RF IN VSWR1 VSWRi1 1.67 VSWRo1 RF OUT VSWR1 1.96

<sup>\*1</sup> Input and output PCB, connector losses:

<sup>0.035</sup>dB(at 170MHz), 0.088dB(at 620MHz), 0.120dB(at 900MHz)

<sup>\*2</sup> Input PCB, connector losses:

<sup>0.018</sup>dB(at 170MHz), 0.044dB(at 620MHz), 0.060dB(at 900MHz)

# ■ ELECTRICAL CHARACTERISTICS 2 RF CHARACTERISTICS2 (Low Gain Mode)

Conditions:  $V_{DD}=1.8V$ ,  $V_{CTL}=0V$ ,  $f_{RF}=170\sim900MHz$ ,  $T_a=+25^{\circ}C$ ,  $Z_s=Z_l=50ohm$ , with application circuit

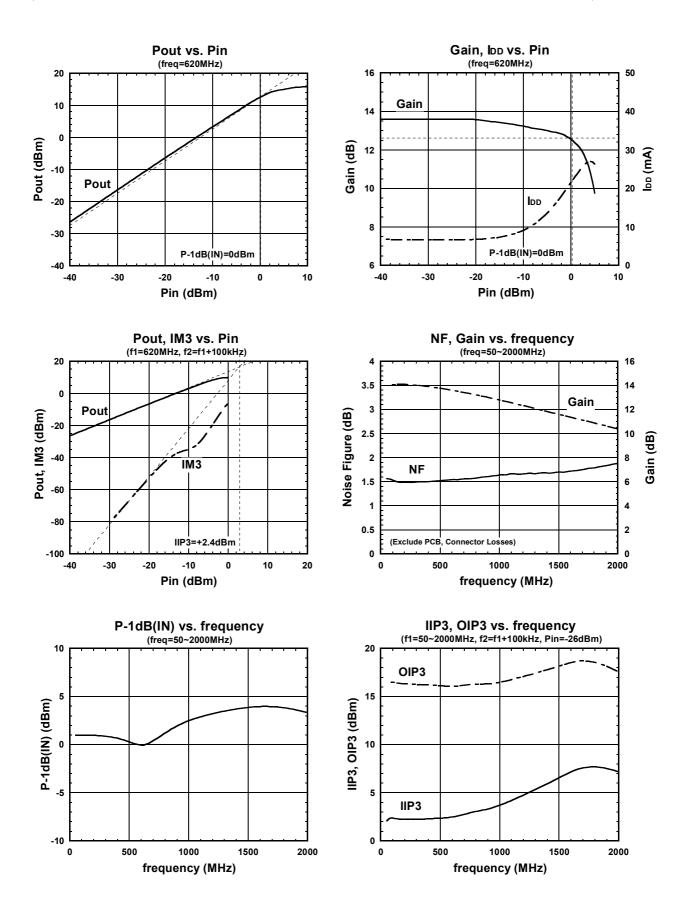
PARAMETERS	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Small signal gain2	Gain2	Exclude PCB & connector losses*1	-	-1.1	1	dB
Input power at 1dB gain compression2	P <sub>-1dB(IN)</sub> 2		-	+18.9	ı	dBm
Input 3rd order intercept point2	IIP3_2	$f1=f_{RF}$ , $f2=f_{RF}+100$ kHz, $P_{IN}=-8$ dBm	-	+24.0	ı	dBm
RF IN VSWR2	VSWRi2		-	1.33	ı	-
RF OUT VSWR2	VSWRo2		-	1.15	-	-

<sup>\*1</sup> Input and output PCB, connector losses : 0.035dB(at 170MHz), 0.088dB(at 620MHz), 0.120dB(at 900MHz)

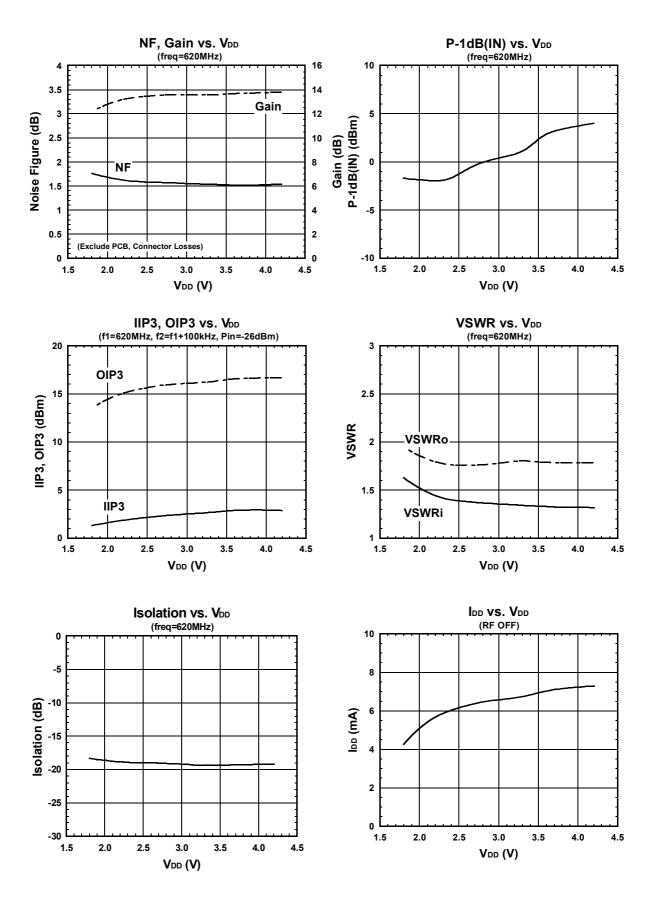
## **TERMINAL INFORMATION**

No.	SYMBOL	DESCRIPTION
1	VCTL	Control voltage supply terminal.
2	GND	Ground terminal. These terminals should be connected to the ground plane as close as possible for excellent RF performance.
3	RFOUT	RF output terminal. This terminal is also the power supply terminal of the LNA. please use inductor (L1) to connect power supply.
4	GND	Ground terminal. These terminals should be connected to the ground plane as close as possible for excellent RF performance.
5	GND	Ground terminal. These terminals should be connected to the ground plane as close as possible for excellent RF performance.
6	RFIN	RF input terminal. This IC is integrated an input DC blocking capacitor.

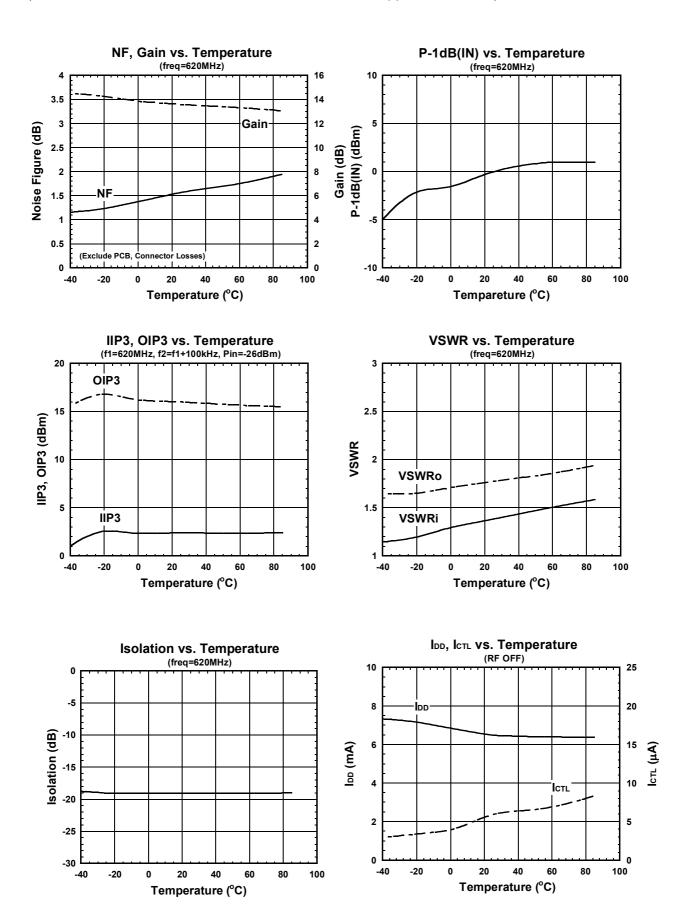
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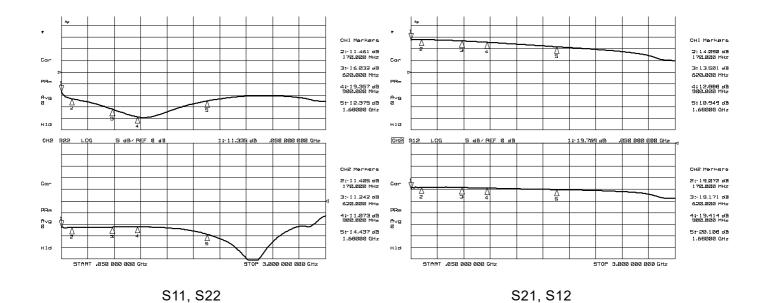
(Condition :Ta=+25°C, V<sub>CTL</sub>=1.8V, Zs=ZI=50ohm, with application circuit)

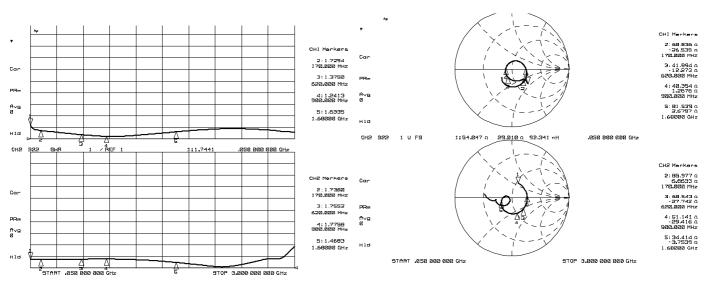


(Condition: V<sub>DD</sub>=2.8V, V<sub>CTL</sub>=1.8V, Zs=Zl=50ohm, with application circuit)



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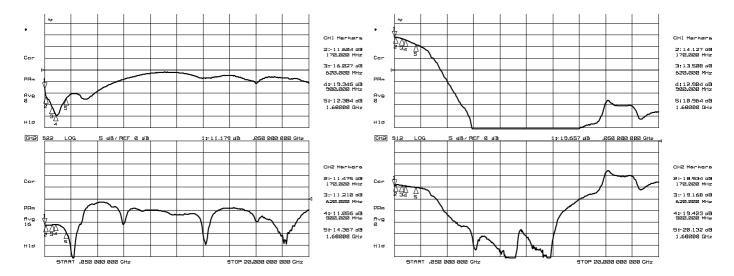


VSWRi, VSWRo Zin, Zout

# **NJG1142KA1**

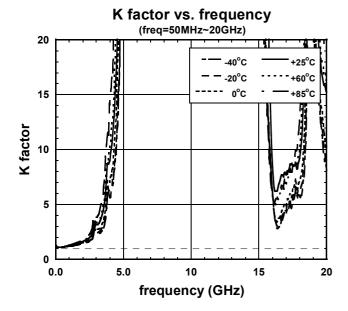
# **■ ELECTRICAL CHARACTERISTICS (High Gain Mode)**

(Condition :Ta=+25°C, V<sub>DD</sub>=2.8V, V<sub>CTL</sub>=1.8V, Zs=ZI=50ohm, with application circuit)

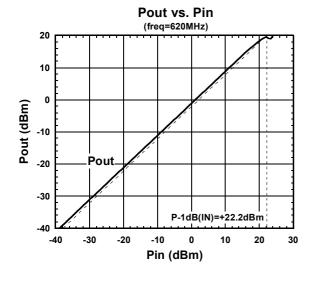


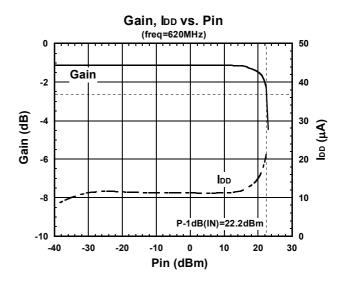
S11, S22 (50MHz~20GHz)

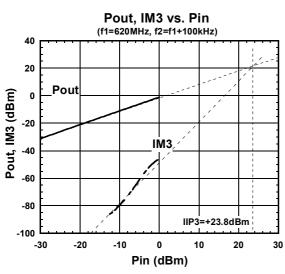
S21, S12 (50MHz~20GHz)

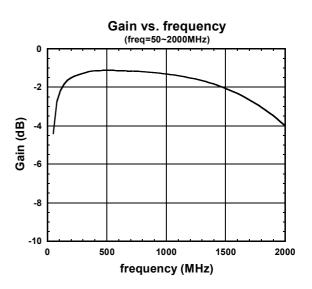


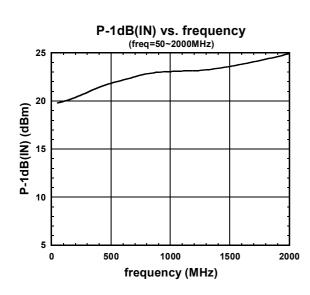
(Condition: Ta=+25°C, V<sub>DD</sub>=2.8V, V<sub>CTL</sub>=0V, Zs=Zl=50ohm, with application circuit)

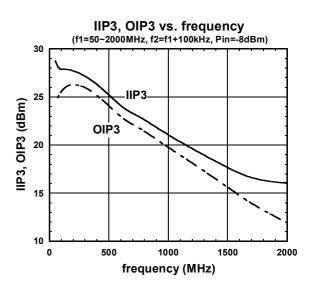




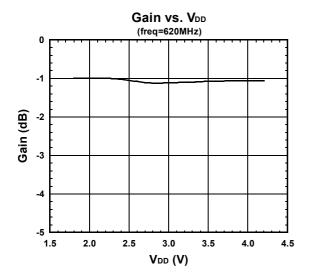


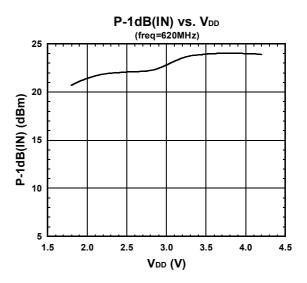


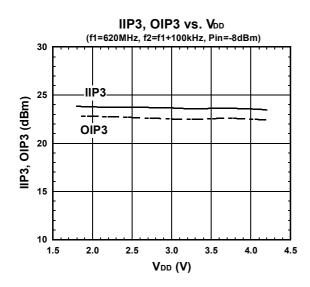


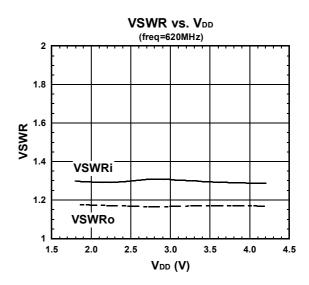


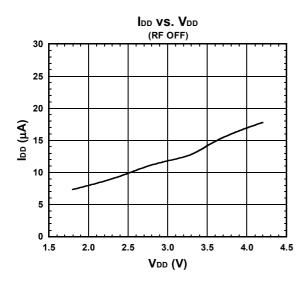
(Condition :Ta=+25°C, V<sub>CTL</sub>=0V, Zs=Zl=50ohm, with application circuit)



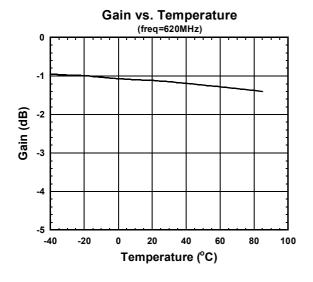


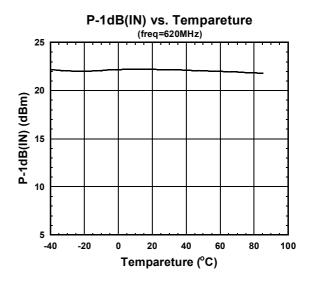


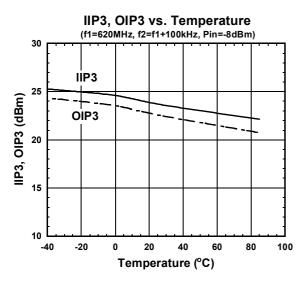


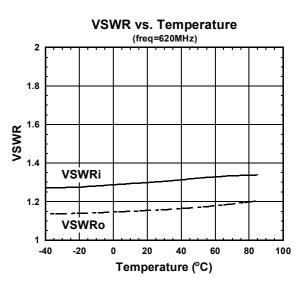


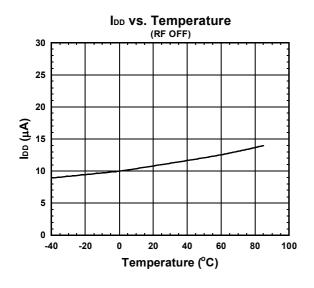
(Condition: V<sub>DD</sub>=2.8V, V<sub>CTL</sub>=0V, Zs=Zl=50ohm, with application circuit)

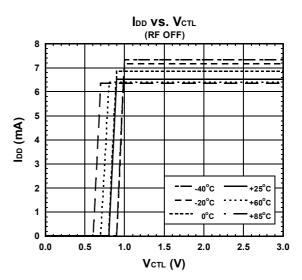




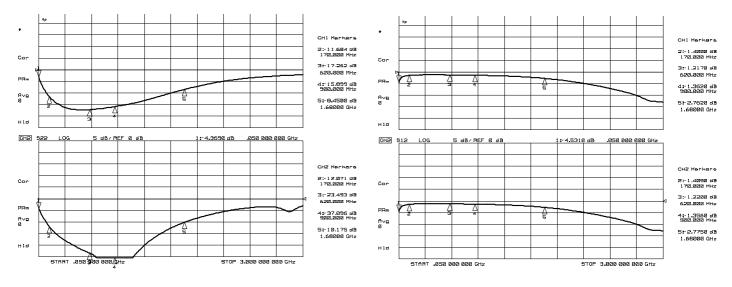




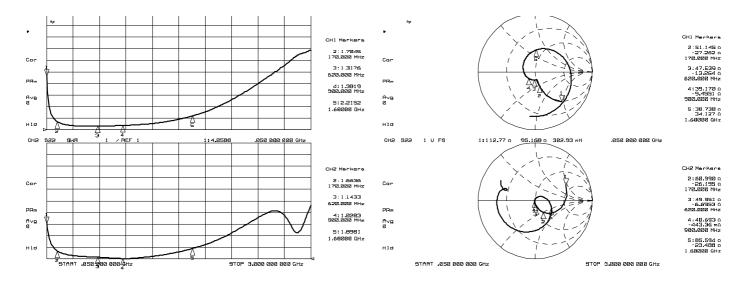




(Condition: Ta=+25°C, V<sub>DD</sub>=2.8V, V<sub>CTL</sub>=0V, Zs=Zl=50ohm, with application circuit)

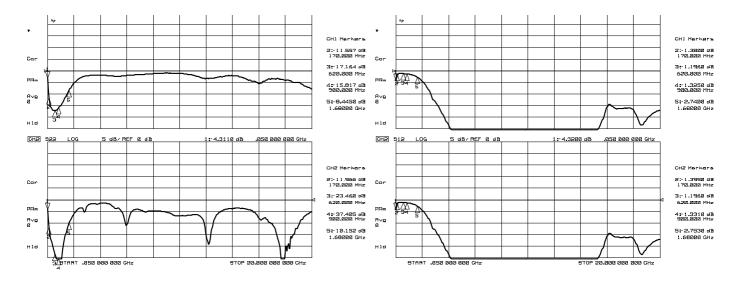


S11, S22 S21, S12



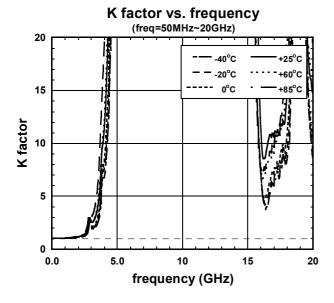
VSWRi, VSWRo Zin, Zout

(Condition :Ta=+25°C, V<sub>DD</sub>=2.8V, V<sub>CTL</sub>=0V, Zs=Zl=50ohm,With application circuit)

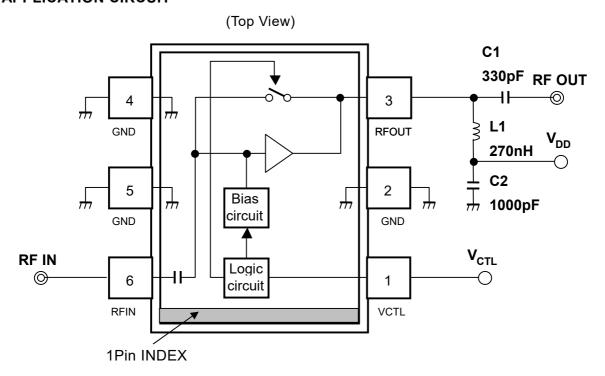


S11, S22 (50MHz~20GHz)

S21, S12 (50MHz~20GHz)



### **■ APPLICATION CIRCUIT**

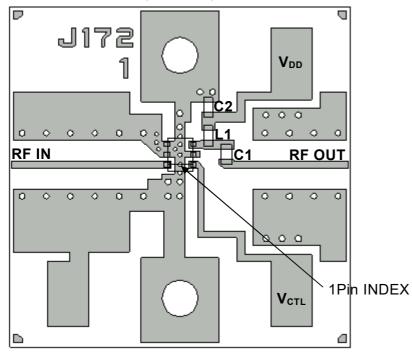


### NOTES:

- · L1 is an RF choke. (DC feed inductor)
- C1 is a coupling and DC blocking capacitor at the output.
- C2 is a bypass capacitor.

### **■ TEST PCB LAYOUT**

(Top View)



#### **■ PARTS LIST**

Parts ID.	Notes
L1	TAIYO-YUDEN HK1005 Series
C1, C2	MURATA GRM15 Series

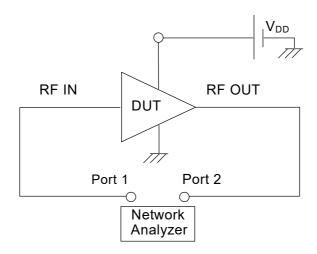
PCB (FR-4): t=0.2mm  $MICROSTRIP\ LINE\ WIDTH$   $=0.40mm\ (Z_0=50\Omega)$   $PCB\ SIZE=16.8mm\ x\ 16.8mm$ 

### PRECAUTION:

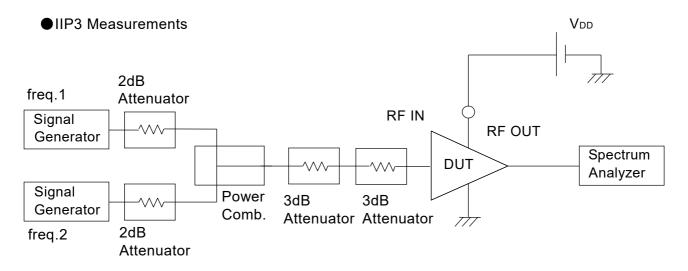
• In order not to couple with terminal RFIN and RFOUT, please layout ground pattern under the IC.

### ■ MEASUREMENT BLOCK DIAGRAM

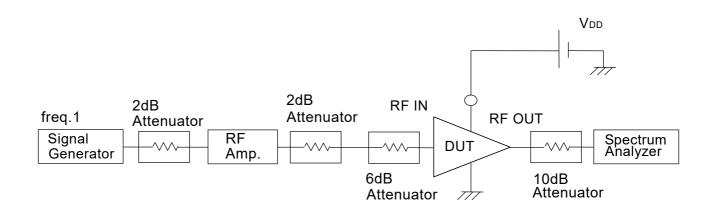
S parameter Measurements



S parameter Measurement Block Diagram



IF and IM3 Measurement Block Diagram for IIP3 (High Gain Mode)



IF and IM3 Measurement Block Diagram for IIP3 (Low Gain Mode)

Nisshinbo Micro Devices Inc.

Noise Figure Measurements

### **Measuring instruments**

NF Analyzer : Agilent 8973A Noise Source : Agilent 346A

### Setting the NF analyzer

Measurement mode form

Device under test : Amplifier

System downconverter: off

Mode setup form

Sideband : LSB

Averages : 8

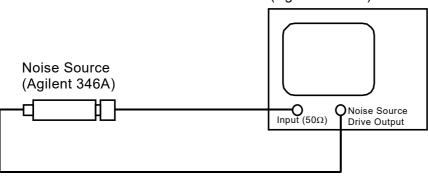
Average mode : Point

Bandwidth : 4MHz

Loss comp : off

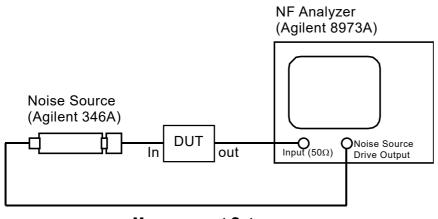
Toold : setting the temperature of noise source (300.0K)

NF Analyzer (Agilent 8973A)



\* Noise source and NF analyzer are connected directly.

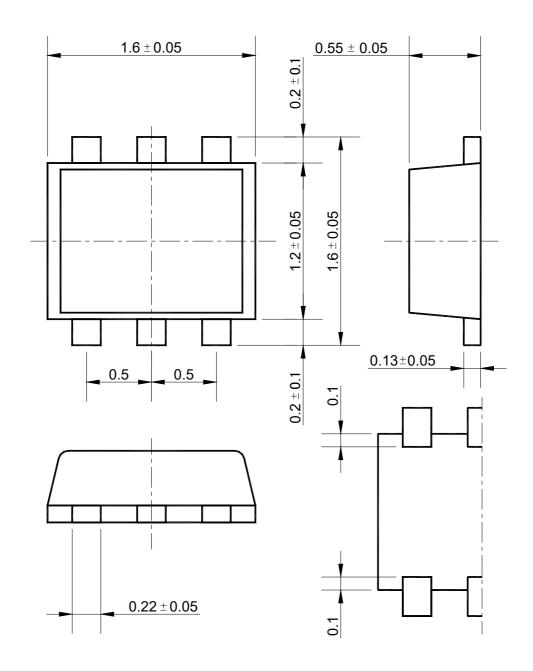
### **Calibration Setup**



\* Noise source and DUT, DUT and NF analyzer are connected directly.

**Measurement Setup** 

## **■ PACKAGE OUTLINE (FLP6-A1)**



Unit: mm

#### Cautions on using this product

This product contains Gallium-Arsenide (GaAs) which is a harmful material.

- Do NOT eat or put into mouth.
- Do NOT dispose in fire or break up this product.
- Do NOT chemically make gas or powder with this product.
- To waste this product, please obey the relating law of your country.

This product may be damaged with electric static discharge (ESD) or spike voltage. Please handle with care to avoid these damages.

#### [CAUTION]

The specifications on this databook are only given for information , without any guarantee as regards either mistakes or omissions. The application circuits in this databook are described only to show representative usages of the product and not intended for the guarantee or permission of any right including the industrial rights.

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  - Aerospace Equipment
  - Equipment Used in the Deep Sea
  - Power Generator Control Equipment (nuclear, steam, hydraulic, etc.)
  - · Life Maintenance Medical Equipment
  - · Fire Alarms / Intruder Detectors
  - Vehicle Control Equipment (automotive, airplane, railroad, ship, etc.)
  - Various Safety Devices
  - Traffic control system
  - Combustion equipment

In case your company desires to use this product for any applications other than general electronic equipment mentioned above, make sure to contact our company in advance. Note that the important requirements mentioned in this section are not applicable to cases where operation requirements such as application conditions are confirmed by our company in writing after consultation with your company.

- 6. We are making our continuous effort to improve the quality and reliability of our products, but semiconductor products are likely to fail with certain probability. In order to prevent any injury to persons or damages to property resulting from such failure, customers should be careful enough to incorporate safety measures in their design, such as redundancy feature, fire containment feature and fail-safe feature. We do not assume any liability or responsibility for any loss or damage arising from misuse or inappropriate use of the products.
- 7. The products have been designed and tested to function within controlled environmental conditions. Do not use products under conditions that deviate from methods or applications specified in this datasheet. Failure to employ the products in the proper applications can lead to deterioration, destruction or failure of the products. We shall not be responsible for any bodily injury, fires or accident, property damage or any consequential damages resulting from misuse or misapplication of the products.
- 8. Quality Warranty
  - 8-1. Quality Warranty Period
    - In the case of a product purchased through an authorized distributor or directly from us, the warranty period for this product shall be one (1) year after delivery to your company. For defective products that occurred during this period, we will take the quality warranty measures described in section 8-2. However, if there is an agreement on the warranty period in the basic transaction agreement, quality assurance agreement, delivery specifications, etc., it shall be followed.
  - 8-2. Quality Warranty Remedies
    - When it has been proved defective due to manufacturing factors as a result of defect analysis by us, we will either deliver a substitute for the defective product or refund the purchase price of the defective product.
    - Note that such delivery or refund is sole and exclusive remedies to your company for the defective product.
  - 8-3. Remedies after Quality Warranty Period
    - With respect to any defect of this product found after the quality warranty period, the defect will be analyzed by us. On the basis of the defect analysis results, the scope and amounts of damage shall be determined by mutual agreement of both parties. Then we will deal with upper limit in Section 8-2. This provision is not intended to limit any legal rights of your company.
- 9. Anti-radiation design is not implemented in the products described in this document.
- 10. The X-ray exposure can influence functions and characteristics of the products. Confirm the product functions and characteristics in the evaluation stage.
- 11. WLCSP products should be used in light shielded environments. The light exposure can influence functions and characteristics of the products under operation or storage.
- 12. Warning for handling Gallium and Arsenic (GaAs) products (Applying to GaAs MMIC, Photo Reflector). These products use Gallium (Ga) and Arsenic (As) which are specified as poisonous chemicals by law. For the prevention of a hazard, do not burn, destroy, or process chemically to make them as gas or power. When the product is disposed of, please follow the related regulation and do not mix this with general industrial waste or household waste.
- 13. Please contact our sales representatives should you have any questions or comments concerning the products or the technical information.



Official website

https://www.nisshinbo-microdevices.co.jp/en/

**Purchase information** 

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